

# Global Semiconductor Package Market 2024 by Company, Regions, Type and Application, Forecast to 2030

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## Abstracts

According to our (Global Info Research) latest study, the global Semiconductor Package market size was valued at USD 29490 million in 2023 and is forecast to a readjusted size of USD 42990 million by 2030 with a CAGR of 5.5% during review period.

Semiconductor packaging is conducted to guarantee protection to the wafer or substrate. The packaging is built from materials such as plastic, metal, glass or ceramic and is composed of one or more semiconductor electronic components.

Semiconductor packaging materials are base players of discrete semiconductor devices and integrated circuits on which other layers are deposited to complete the circuit. Thinner core materials are ideally used to surro system applications.

The validation of lead substrates has increased in comparison to lead frames and bonding wires as the industry advances more towards leadless and cable-less packages.

The market will experience robust growth due to increased demand for smart mobile devices and electronic goods.

Following a strong growth of 26.2 percent in the year 2021, WSTS revised it down to a single digit growth for the worldwide semiconductor market in 2022 with a total size of US\$580 billion, up 4.4 percent. WSTS lowered growth estimation as inflation rises and end markets seeing weaker demand, especially those exposed to consumer spending. While some major categories are still double-digit year-over-year growth in 2022, led by Analog with 20.8 percent, Sensors with 16.3 percent, and Logic with 14.5 percent

growth. Memory declined with 12.6 percent year over year. In 2022, all geographical regions showed double-digit growth except Asia Pacific. The largest region, Asia Pacific, declined 2.0 percent. Sales in the Americas were US\$142.1 billion, up 17.0% year-on-year, sales in Europe were US\$53.8 billion, up 12.6% year-on-year, and sales in Japan were US\$48.1 billion, up 10.0% year-on-year. However, sales in the largest Asia-Pacific region were US\$336.2 billion, down 2.0% year-on-year.

The Global Info Research report includes an overview of the development of the Semiconductor Package industry chain, the market status of Consumer Electronics (Flip Chip, Embedded Die), Automotive Industry (Flip Chip, Embedded Die), and key enterprises in developed and developing market, and analysed the cutting-edge technology, patent, hot applications and market trends of Semiconductor Package.

Regionally, the report analyzes the Semiconductor Package markets in key regions. North America and Europe are experiencing steady growth, driven by government initiatives and increasing consumer awareness. Asia-Pacific, particularly China, leads the global Semiconductor Package market, with robust domestic demand, supportive policies, and a strong manufacturing base.

#### Key Features:

The report presents comprehensive understanding of the Semiconductor Package market. It provides a holistic view of the industry, as well as detailed insights into individual components and stakeholders. The report analysis market dynamics, trends, challenges, and opportunities within the Semiconductor Package industry.

The report involves analyzing the market at a macro level:

**Market Sizing and Segmentation:** Report collect data on the overall market size, including the revenue generated, and market share of different by Type (e.g., Flip Chip, Embedded Die).

**Industry Analysis:** Report analyse the broader industry trends, such as government policies and regulations, technological advancements, consumer preferences, and market dynamics. This analysis helps in understanding the key drivers and challenges influencing the Semiconductor Package market.

**Regional Analysis:** The report involves examining the Semiconductor Package market at a regional or national level. Report analyses regional factors such as government

incentives, infrastructure development, economic conditions, and consumer behaviour to identify variations and opportunities within different markets.

**Market Projections:** Report covers the gathered data and analysis to make future projections and forecasts for the Semiconductor Package market. This may include estimating market growth rates, predicting market demand, and identifying emerging trends.

The report also involves a more granular approach to Semiconductor Package:

**Company Analysis:** Report covers individual Semiconductor Package players, suppliers, and other relevant industry players. This analysis includes studying their financial performance, market positioning, product portfolios, partnerships, and strategies.

**Consumer Analysis:** Report covers data on consumer behaviour, preferences, and attitudes towards Semiconductor Package. This may involve surveys, interviews, and analysis of consumer reviews and feedback from different by Application (Consumer Electronics, Automotive Industry).

**Technology Analysis:** Report covers specific technologies relevant to Semiconductor Package. It assesses the current state, advancements, and potential future developments in Semiconductor Package areas.

**Competitive Landscape:** By analyzing individual companies, suppliers, and consumers, the report present insights into the competitive landscape of the Semiconductor Package market. This analysis helps understand market share, competitive advantages, and potential areas for differentiation among industry players.

**Market Validation:** The report involves validating findings and projections through primary research, such as surveys, interviews, and focus groups.

## Market Segmentation

Semiconductor Package market is split by Type and by Application. For the period 2019-2030, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of value.

## Market segment by Type

Flip Chip

Embedded Die

Fan-in Wafer Level Packaging (Fi Wlp)

Fan-out Wafer Level Packaging

Others

#### Market segment by Application

Consumer Electronics

Automotive Industry

Aerospace and Defense

Medical Devices

Communications and Telecom

Others

#### Market segment by players, this report covers

SPIL

ASE

Amkor

JCET

TFME

Siliconware Precision Industries

Powertech Technology Inc

TSMC

Nepes

Walton Advanced Engineering

Unisem

Huatian

Chipbond

UTAC

Chipmos

China Wafer Level CSP

Lingsen Precision

Tianshui Huatian Technology Co., Ltd

King Yuan Electronics CO., Ltd.

Formosa

Carsem

J-Devices

Stats Chippac

Advanced Micro Devices

Market segment by regions, regional analysis covers

North America (United States, Canada, and Mexico)

Europe (Germany, France, UK, Russia, Italy, and Rest of Europe)

Asia-Pacific (China, Japan, South Korea, India, Southeast Asia, Australia and Rest of Asia-Pacific)

South America (Brazil, Argentina and Rest of South America)

Middle East & Africa (Turkey, Saudi Arabia, UAE, Rest of Middle East & Africa)

The content of the study subjects, includes a total of 13 chapters:

Chapter 1, to describe Semiconductor Package product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top players of Semiconductor Package, with revenue, gross margin and global market share of Semiconductor Package from 2019 to 2024.

Chapter 3, the Semiconductor Package competitive situation, revenue and global market share of top players are analyzed emphatically by landscape contrast.

Chapter 4 and 5, to segment the market size by Type and application, with consumption value and growth rate by Type, application, from 2019 to 2030.

Chapter 6, 7, 8, 9, and 10, to break the market size data at the country level, with revenue and market share for key countries in the world, from 2019 to 2024. and Semiconductor Package market forecast, by regions, type and application, with consumption value, from 2025 to 2030.

Chapter 11, market dynamics, drivers, restraints, trends and Porters Five Forces analysis.

Chapter 12, the key raw materials and key suppliers, and industry chain of Semiconductor Package.

Chapter 13, to describe Semiconductor Package research findings and conclusion.

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